

## United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER OF PATENTS AND TRADEMARKS Washington, D.C. 20231 www.uspto.gov

APPLICATION NO.	FI	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO	CONFIDNATION
09/632,910		08/04/2000		ATTORNET BOCKET NO.	ONFIRMATION NO.
,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		070-72000	Kohei Tatsumi	52433/609  EXAMINER  CHAMBLISS, A  ART UNIT  2827	1969
26646	7590	09/30/2002	•		
KENYON &	KENY	ON			
ONE BROAD			EXAMINER		
NEW YORK,	NY 100	004		CHAMBLISS	, ALONZO
				ART UNIT	PAPER NUMBER
				2827	
				DATE MAILED: 09/30/2002	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	am
Advisory Action	09/632,910	TATSUMI ET AL.	
, and any reduction	Examiner	Art Unit	
	Alonzo Chambliss	2027	
The MAILING DATE of this communication app	ears on the cover sheet wi	th the correspondence ad	draga
herefore, further action by the applicant is required to a inal rejection under 37 CFR 1.113 may only be either: (1 condition for allowance; (2) a timely filed Notice of Appearamination (RCE) in compliance with 37 CFR 1.114.	PLICATION IN CONDITIOn word abandonment of this is a timely filed amendment of the appeal fee); or (3) is a (with appeal fee); or (3) is a contract of the contract of the appeal fee); or (3) is a contract of the contract o	N FOR ALLOWANCE. application. A proper rep nt which places the applic a timely filed Request for	du to o
PERIOD FOR RE	EPLY [check either a) or b	)]	
a) The period for reply expires 5 months from the mailing date b) The period for reply expires on: (1) the mailing date of this A no event, however, will the statutory period for reply expire I ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS 706.07(f).  Extensions of time may be obtained under 37 CFR 1.136(a). The e have been filed is the date for purposes of determining the period of	Advisory Action, or (2) the date s later than SIX MONTHS from the S FILED WITHIN TWO MONTHS	S OF THE FINAL REJECTION.	ion. See MPEP
o allowed 57 GH (1.77(a) is calculated from: (1) the expiration date of to asset forth in (b) above, if checked. Any reply received by the Officenely filed, may reduce any earned patent term adjustment. See 37 C	the shortened statutory period for the later than three months after the FR 1.704(b).	or reply originally set in the final the mailing date of the final reje	
A Notice of Appeal was filed on Appellant's 37 CFR 1.192(a), or any extension thereof (37 CFR	( I. 191(0)). TO avoid dismi	the period set forth in ssal of the appeal.	,
The proposed amendment(s) will not be entered be	cause:		
(a) ☐ they raise new issues that would require furthe	r consideration and/or sea	arch (see NOTF below)	
Note be	elow).		
(c) ☑ they are not deemed to place the application in issues for appeal; and/or			
(d) they present additional claims without cancelin NOTE:		r of finally rejected claims	
Applicant's reply has overcome the following rejectio	on(s):		
Newly proposed or amended claim(s) would b canceling the non-allowable claim(s).	e allowable if submitted in	a separate, timely filed a	mendment
☐ The a)☐ affidavit, b)☐ exhibit, or c)☐ request for reapplication in condition for allowance because:	*		
The affidavit or exhibit will NOT be considered becauraised by the Examiner in the final rejection.			
For purposes of Appeal, the proposed amendment(s explanation of how the new or amended claims wou.	) a)⊠ will not be entered ld be rejected is provided	or b)∏ will be entered an	d an
The status of the claim(s) is (or will be) as follows:			
Claim(s) allowed:	Ļ	KAMAND CUNEO	
Claim(s) objected to:	SÚI	PERVISORY PATENT EXAMI	NFR
Claim(s) rejected: <u>16-26</u> .	•	<b>TECHNOLOGY CENTER 280</b>	0
Claim(s) withdrawn from consideration:			
The proposed drawing correction filed on is a)[	approved or b) dis	annroyed by the Evamina	_
Note the attached Information Disclosure Statement(s	s)( PTO-1449) Paper No/s	el	1.
Other: See Continuation Sheet	-/(	· · · · · · · · · · · · · · · · · · ·	
<del></del>			

Continuation of 10. Other: As mention in the Final rejection, Juskey discloses that the solder bumps can be used with a chip carrier or other members that are well known in the art. One skilled in the art would readily recognize that a semiconductor chip would be considered as an other member, since a semiconductor chip is formed from a wafer substrate that has been sliced into individual chips. Thus, the electrodes as claimed by the applicant can be formed on the chip in the manner as taught by Juskey. Furthermore, Juskey discloses a flip chip connection, since the solder blow is first attached to the chip by reflow that is readily recognize to one skilled in the art and then flip to a position that is seen in Fig. 3